

The invention relates to field of powder metallurgy, in particular to diamond-hard metal alloy plates and may be used at agglomeration of permanent layered connections hard metal alloy substrate – diamond polycrystal in conditions of high pressure and temperature. Diamond-hard metal alloy plate contains diamond layer and hard metal alloy plate between which is located an intermediate layer containing diamonds. Diamond layer additionally contains silicon carbide and silicon and intermediate layer additionally contains cobalt silicide at following ratio of components (in per cent by weight):

diamond layer:

diamonds	89 - 97
silicon carbide	2,8 - 9
silicon	0,2 - 2

intermediate layer:

cobaltsilicide (CoSi_2)	10 - 38
diamonds	62 – 90.

In the best embodiment of invention the thickness of intermediate layer makes 0.15 – 0.25 of thickness of diamond layer. The invention provides for regular arrangement of components in diamond layer, improvement of bond between diamond grains, creation of intermediate barrier layer that at agglomeration of diamond-hard metal alloy plate opposes to dripping of cobalt into diamond layer and such structure provides for increase of thermal resistance of material.